



S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Assignee:	Intel Corporation	Customer No:	21186

COMMUNICATION REGARDING SUBMISSION OF RCE UNDER 37 C.F.R. 1.114
AND WITHDRAWAL OF APPLICATION FROM APPEAL

MS Appeal Brief - Patents
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This communication is to inform the Board of Patent Appeals and Interferences that Applicants' are concurrently submitting a Request for Continued Examination Under 37 C.F.R. 1.114 and Information Disclosure Statement, including the fee set forth in 37 C.F.R. 1.17(e), thereby effectively withdrawing the above-identified patent application from appeal. A copy of the transmittal listing same is enclosed.

The Examiner is invited to telephone Applicant's attorney, John Greaves at (801) 278-9171, or Applicant's below-named representative at (612) 373-6970 to facilitate the prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

XIAO-CHUN MU ET AL.

By their Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, Minnesota 55402
(612) 373-6970

Date

January 4, 2005

By

Charles E. Steffey

Charles E. Steffey

Reg. No. 25,179

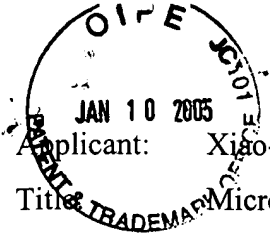
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Appeal Brief - Patents, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 4 day of January, 2005.

Name

Chris Hammond

Signature

Chris Hammond



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Docket No.: 884.798US1

Serial No.: 09/733,289

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Due Date: N/A

Examiner: DiLinh Nguyen

Group Art Unit: 2814

Mail Stop Appeal Brief--Patents

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ Communication Regarding Submission of RCE Under 37 C.F.R. 1.114 and Withdrawal of Application From Appeal (1 pg.).
- ☒ COPY of transmittal listing RCE and IDS filed on same date (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: 

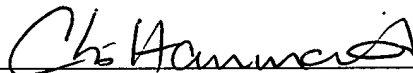
Atty: Charles E. Steffey

Reg. No. 25,179

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Name



Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)